

**REMARKS**

The Examiner's Action mailed on March 25, 2005, has been received and its contents carefully considered.

In this Amendment, Applicant has editorially amended the specification, and amended claims 1, 2, 5, 9, 13, 14 and 15. The changes to the claims have not been made in order to help define over the art of record, but instead have only been made in order to correct informalities noted during the review, and to better recite the invention. Claims 1 and 9 are the independent claims, and claims 1-18 remain pending in the application. For at least the following reasons, it is submitted that this application is in condition for allowance.

Initially, it is noted with great appreciation that the Examiner considers claims 9-13 and 15-18 as being allowed, and the subject matter of dependent claims 7, 8 and 14 as being allowable over the art of record. However, because independent claim 1 is believed to be patentably distinguishable over the cited reference, dependent claims 7, 8 and 14 have not been re-written into independent form.

The Examiner has rejected claims 1-6 as being anticipated by *Kanemoto et al.* (USP 6,410,987). It is submitted that these claims are *prima facie* patentably distinguishable over the cited reference for at least the following reasons.

It is well settled that a reference may anticipate a claim within the purview of 35 U.S.C. § 102 only if all the features and all the relationships recited in the

claim are taught by the referenced structure either by clear disclosure or under the principle of inherency.

Applicant's independent claim 1 is directed to a multi-chip package which includes, *inter alia*, an auxiliary lead which supports a first semiconductor chip. The auxiliary lead supports the first semiconductor chip at a corner of the chip and extends towards an outside of the chip. This claimed configuration ensures that a wire that connects a lead and a bonding pad will not pass over the auxiliary lead. Moreover, this configuration also allows the leads to be arranged on each of the four sides of the chip, allowing the leads to be arranged over a relatively large space, so that it is possible to bring the leads close to the bonding pads to thereby reduce the height of the wire (see page 5, line 20 through page 6, line 14). This claimed configuration is neither disclosed nor suggested by the cited reference.

*Kanemoto et al.* disclose a multi-chip package that includes support leads 6. The support leads 6 include suspended lead portions 6A and chip support lead portions 6B (see column 13, lines 26 through 36, and figure 1). The chip support lead portions 6B have a rectangular configuration and are bonded to a circuit forming surface 3X of a chip 3 (see column 13, lines 56 through 58).

However, and in contrast to the present invention, the suspended lead portions 6A (which the Examiner considers to be an auxiliary lead) do not support the chip at a corner of the chip, as recited by claim 1. Instead, the suspended lead portions 6A are disposed in a location set away from the corners of the chip. Moreover, whereas claim 1 recites that the wires do not pass over the auxiliary

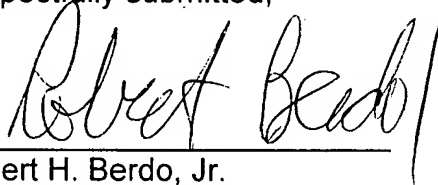
lead, this reference clearly discloses that the wires do, in fact, pass over the suspended lead portions 6A, as well as over the chip support lead portions 6B. Thus, the configuration disclosed by *Kanemoto et al.* would not enjoy the advantages associated with Applicant's claimed invention. As such, it is submitted that Applicant's independent claim 1 is *prima facie* patentably distinguishable over the cited reference and it is therefore requested that this claim, and the claims dependent therefrom, be allowed and that these rejections be withdrawn.

It is submitted that this application is in condition for allowance. Such action and the passing of this case to issue are requested.

Should the Examiner feel that a conference would help to expedite the prosecution of this application, the Examiner is hereby invited to contact the undersigned counsel to arrange for such an interview.

Should any fee be required, the Commissioner is hereby authorized to charge the fee to our Deposit Account No. 18-0002, and advise us accordingly.

Respectfully submitted,



Robert H. Berdo, Jr.  
Registration No. 38,075  
RABIN & BERDO, PC  
Customer No. 23995  
Telephone: 202-371-8976  
Facsimile: 202-408-0924

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Date

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